



**SPECIALTY COATING SYSTEMS™**

*A KISCO Company*



# **Atomic Layer Deposition + Parylene Conformal Nanocoatings for Robust Corrosion Protection of Electronics**

**Rakesh Kumar<sup>1</sup> and Shuichi Sawada<sup>2</sup>**

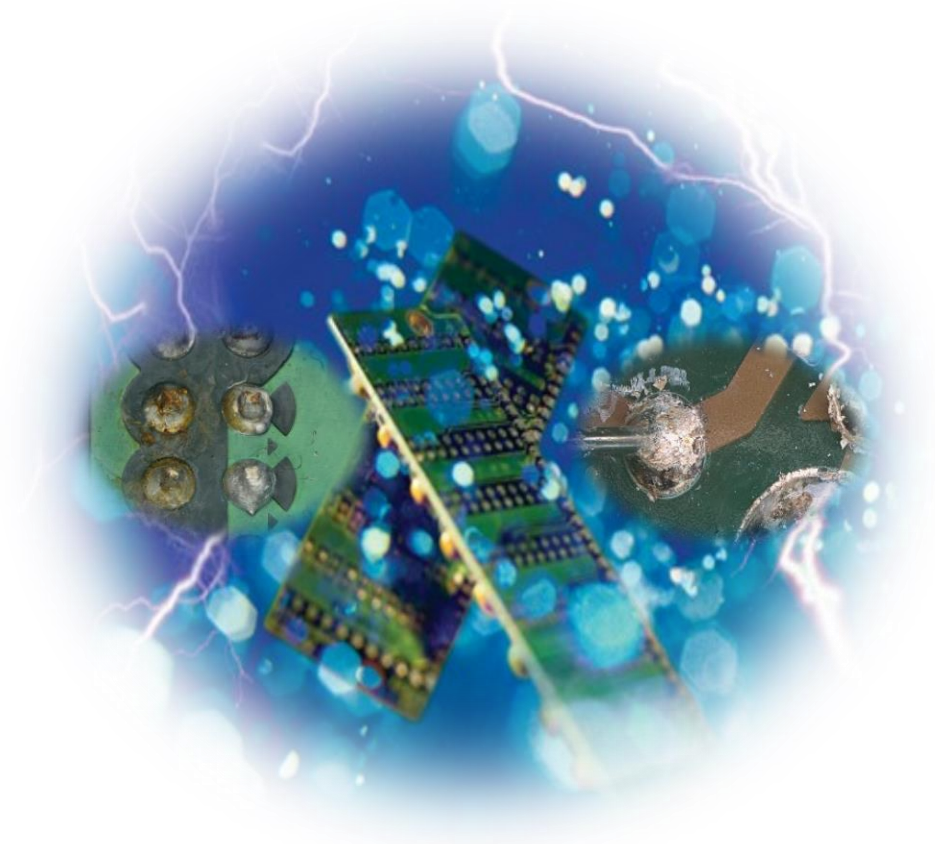
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<sup>2</sup>Daisan Kasei Co., Ltd., Japan

# Outline

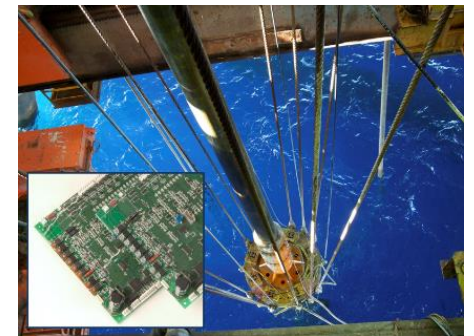
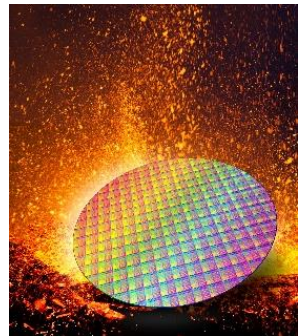
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- ▶ Challenges of electronics
  - Protection and reliability
- ▶ ALD conformal coating
  - A nanoscale precision coating
  - ALD-Parylene for best protection
- ▶ Protection performance evaluation
  - High performance, protection and reliability enhancement
- ▶ Conclusion



# Challenges of Electronics

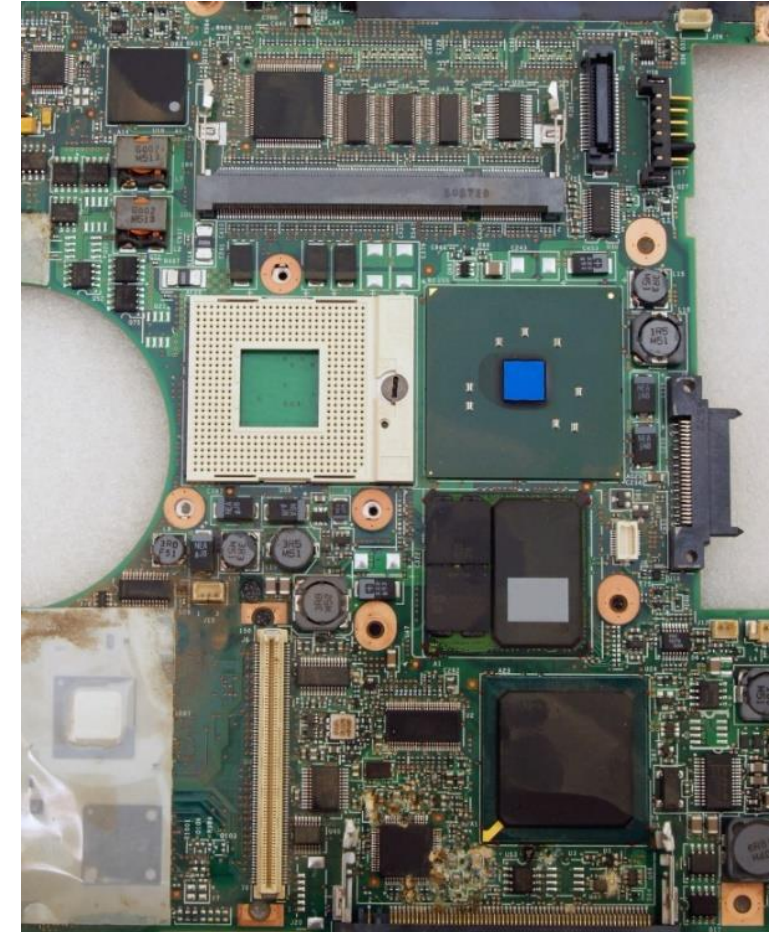
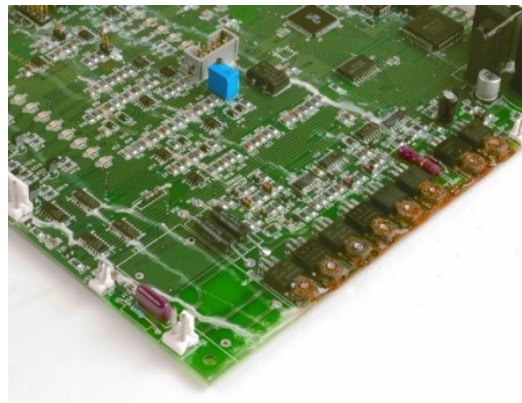
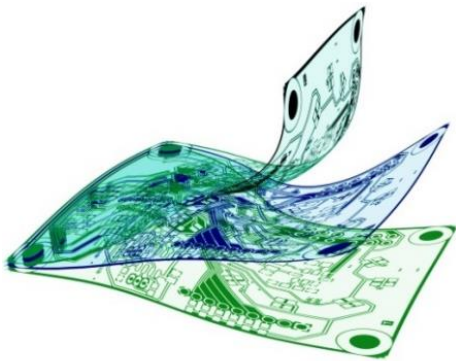
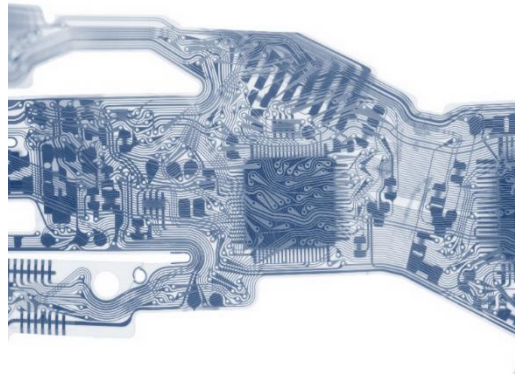
- ▶ Design oversights
  - Insufficient clearances or incorrect measurements
- ▶ Manufacturing/assembly process
  - Bad soldering, loose components, flux residues, traces and pathways
- ▶ Protection and reliability
  - Environmental: Moisture, temperature, dirt & debris, corrosive chemicals
  - Higher operating temperatures, higher frequency operations
  - Electromigration/short circuit
  - Transient electrical stresses/failure
  - Mechanical shock and vibration
  - Metallic whiskers
  - Controlling degradation due to time, physical and chemical attack
  - Industry and government regulatory compliance





# Environmental Challenges: Moisture, temperature, dirt & debris, corrosive chemicals

- ▶ Environmental
  - Water
  - Other corrosive environments



# SCS Sustainable Conformal Coating Technologies

Chemical Vapor Deposition Parylene Coatings	PE Chemical Vapor Deposition Plasma Coatings	Atomic layer deposition(ALD) ALD+Parylene Coatings
<b>Molecular level deposition</b> (0.5 - 50 microns)	<b>Atomic/molecular level deposition</b> (10 nm – 3 microns )	<b>Atomic/molecular level deposition</b> (1 - 100 nanometer)
<ul style="list-style-type: none"> <li>Moisture &amp; chemical barrier</li> <li>Corrosion protection in harsh environment</li> <li>Biocompatible</li> <li>High dielectric strength</li> <li>Chemically inert</li> </ul>	<ul style="list-style-type: none"> <li>Water repellent</li> <li>Hydrophobic</li> <li>Low power insulating organic coating</li> <li>Corrosion protection</li> </ul>	<ul style="list-style-type: none"> <li>Dense</li> <li>Smooth</li> <li>Dielectric and insulating</li> <li>Inorganic nanocoating</li> <li>Corrosion protection in harsh Environment</li> </ul>
<ul style="list-style-type: none"> <li>Unique combination of performance, protection &amp; durability characteristics</li> </ul>	<ul style="list-style-type: none"> <li>Low cost, nanocoating for protection of consumer electronics and medical devices</li> </ul>	<ul style="list-style-type: none"> <li>Improved corrosion resistance / barrier performance against water vapor and gases</li> </ul>
<b>Applications:</b> Electronics, medical and other substrates for high reliability & protection	<b>Applications:</b> Consumer products (electronics, medical devices, flexible devices)	<b>Applications:</b> Consumer products (electronics, medical devices, flexible devices)

# Atomic Layer Deposition (ALD) Coating

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- ▶ Ultra-thin, highly conformal coating at the nanometer and sub-nanometer level
- ▶ Vapor-phase technique where coating formation is via sequential cycling of self-limiting chemical half-reactions on the substrate surface, resulting in a nanoscale precision coating
- ▶ Key Advantages of ALD
  - High-quality films
  - Conformality
  - Gentle deposition process for sensitive substrates
  - Inherent film quality associated with self-limiting
  - Self-assembled nature of the ALD mechanism

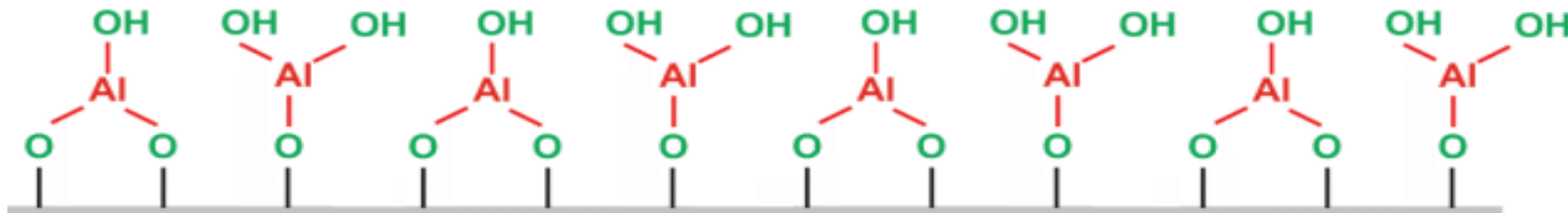
# ALD Types

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- ▶ Thermal ALD
  - Requires temperature more than 100°C and can go up to 350°C
  - Many sub-types that use thermal or classical ALD
    - Metal ALD
    - Particle ALD
- ▶ Plasma-enhanced ALD (PE-ALD)
  - Processing at temperature below 100 °C
- ▶ Electron-enhanced ALD (EE-ALD)
  - Processing at 25-100°C
- ▶ Photo-assisted ALD

# Why ALD-Parylene for Protection?

- ▶ ALD advantages for electronics
  - The coating thickness is homogeneous, controllable to sub-nanometer level
  - 3D conformality, high film density
  - Atomically flat and smooth surface coating
  - Organic and inorganic film can be formed
  - Coating can be formed at room to very low temperatures
  - Excellent barrier properties at ultra-thin (Angstrom) level



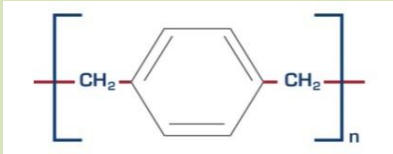
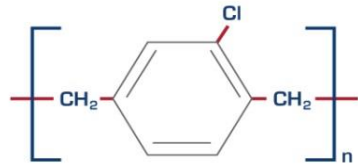

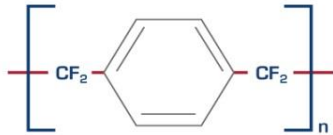


# Why ALD-Parylene for Protection?

- ▶ Parylenes are known to provide better protection and reliability to electronics compared to liquid conformal coatings
- ▶ Parylene advantages for electronics
  - Vapor-phase deposition results in complete coverage, even beneath and around closely-spaced wires and chips
  - Envelops and reinforces fragile wire bonds, strong mechanical strength
  - Among the best coatings for moisture impermeability
  - Coating process at room temperature
  - No by-products are released during polymerization
  - Parylenes have low dielectric constant, low dissipation factor and high electrical insulation resistance
  - Biocompatible and biostable

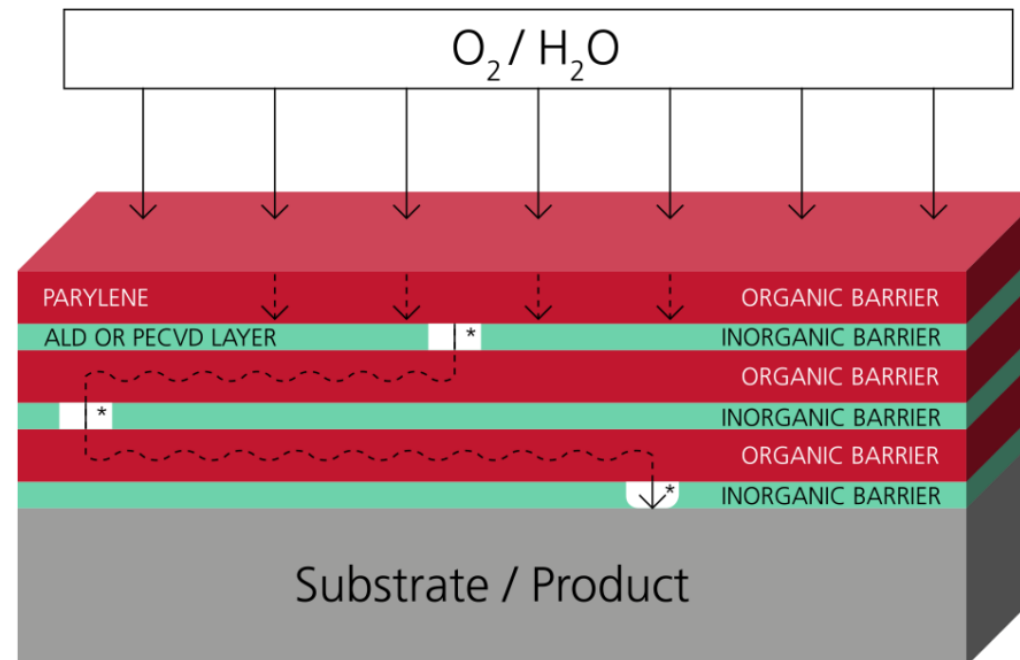


# WW Commercially Available Sustainable Parylene Types

Parylene N	Parylene C	ParyFree®	Parylene HT®
			
<p>Dielectric strength: 7,000V @ 25µm</p> <p>Continuous service temp.: 60°C</p> <p>Short term (≤24 hrs.): 80°C</p> <p>Crevice penetration: 40X</p> <p>COF: 0.25</p> <p>Certifications:</p> <ul style="list-style-type: none"> <li>• IPC-CC-830, MIL-I-46058C and listed on the QPL</li> <li>• <b>USP Class VI</b></li> <li>• <b>ISO-10993 biological evaluation</b></li> </ul>	<p>Dielectric strength: 5,600V @ 25µm</p> <p>Continuous service temp.: 80°C</p> <p>Short term (≤24 hrs.): 100°C</p> <p>Crevice penetration: 5X</p> <p>COF: 0.29</p> <p>Excellent chemical resistance</p> <p>Lowest permeability to moisture and gases</p> <p>Certifications:</p> <ul style="list-style-type: none"> <li>• IPC-CC-830, MIL-I-46058C and listed on the QPL</li> <li>• <b>USP Class VI</b></li> <li>• <b>ISO-10993 biological evaluation.</b></li> </ul>	<p>Dielectric strength: 6900V @ 25µm</p> <p>Continuous service temp.: 60°C</p> <p>Short term (≤24 hrs.): 80°C</p> <p>Crevice penetration: 10X</p> <p>COF: 0.23</p> <p>Excellent chemical resistance</p> <p>Lowest permeability to moisture and gases</p> <p>High Thermal Conductivity</p> <p>Certifications:</p> <ul style="list-style-type: none"> <li>• IPC-CC-830, MIL-I-46058C and listed on the QPL</li> <li>• <b>USP Class VI</b></li> <li>• <b>ISO-10993 biological evaluation</b></li> </ul>	<p>Dielectric strength: 5,400V @ 25µm</p> <p>Highest continuous service temp.: 350°C</p> <p>Short term (≤24 hrs.): 450°C</p> <p>Crevice penetration: 50X</p> <p>COF: 0.13</p> <p>UV stable</p> <p>Lowest dielectric constant &amp; dissipation factor</p> <p>Certifications:</p> <ul style="list-style-type: none"> <li>• IPC-CC-830, MIL-I-46058C and listed on the QPL</li> <li>• <b>USP Class VI</b></li> <li>• <b>ISO-10993 biological evaluation</b></li> </ul>

# Why ALD-Parylene for Protection?

- ▶ Considering the unique properties of both ALD and Parylene, a combination of both at ultra-thin levels can provide better and enhanced protection and reliability to various electronics and components
- ▶ Defects or pinholes are decoupled leading to increased barrier performances



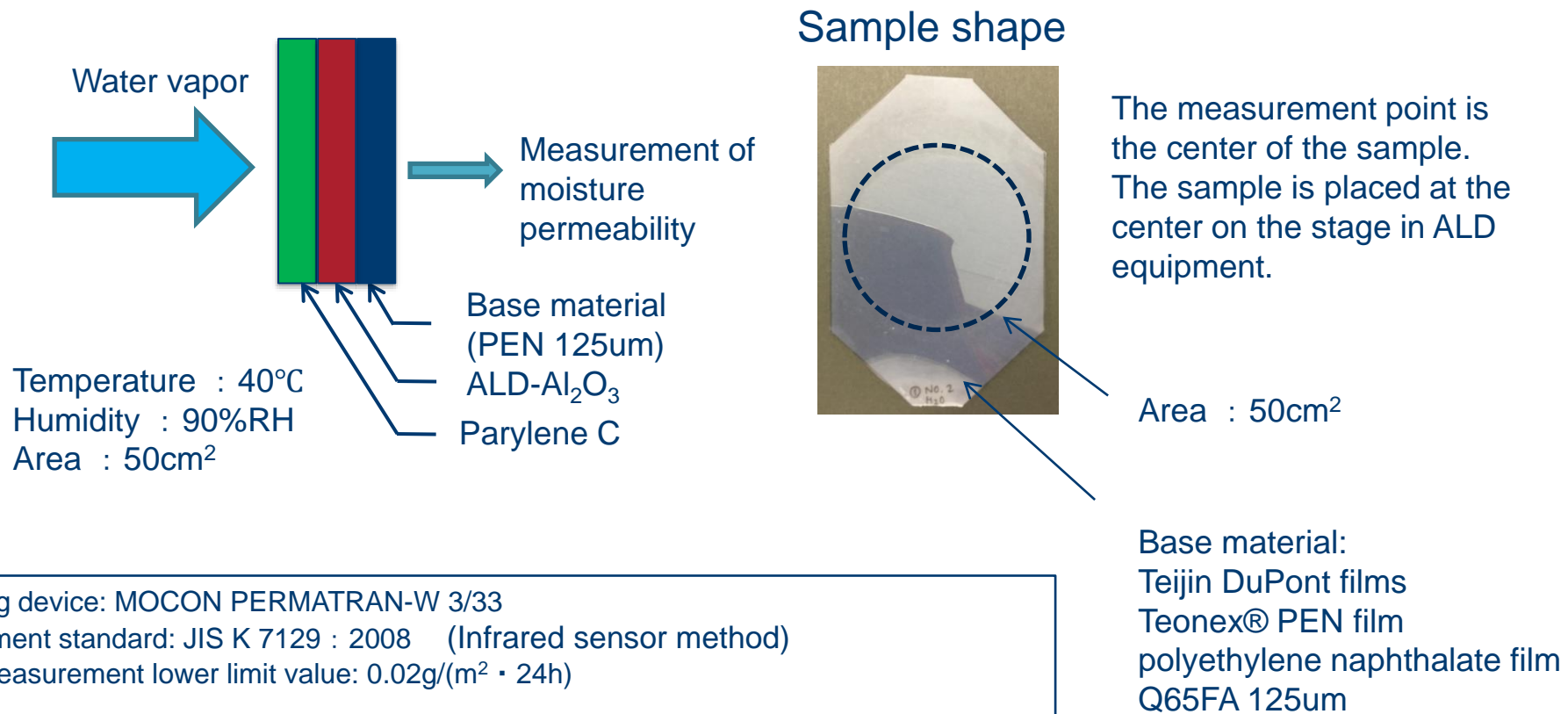
# Protection Performance Evaluation





# Protection Performance Evaluation


## ► Study of Water Vapor Transmission Rate (WVTR)



# WVTR: ALD-Al<sub>2</sub>O<sub>3</sub> + diX C Multi-layer film

- ▶ WVTR of Parylene C improves 63 times due to ALD layer

Deposition Condition	WVTR [g.mm/(m <sup>2</sup> .24h)] 40°C/90%RH
Reference (PEN film)	0.21
Parylene C 25 µm	0.17
Parylene C 10 µm	0.19
Parylene C 5 µm	0.18
Parylene C 0.5 µm	0.19
Parylene N 10 µm	0.22
1 <sup>st</sup> layer Al <sub>2</sub> O <sub>3</sub> 10nm + 2 <sup>nd</sup> layer Parylene C 10 µm	0.009
1 <sup>st</sup> layer Al <sub>2</sub> O <sub>3</sub> 10nm + 2 <sup>nd</sup> layer Parylene C 0.5 µm	0.004
1 <sup>st</sup> layer Parylene C 10 µm + 2 <sup>nd</sup> layer Al <sub>2</sub> O <sub>3</sub> 10nm	0.026
1 <sup>st</sup> layer Al <sub>2</sub> O <sub>3</sub> 18nm + 2 <sup>nd</sup> layer Parylene C 0.5 µm	0.003
1 <sup>st</sup> layer Al <sub>2</sub> O <sub>3</sub> /10 nm + 2 <sup>nd</sup> layer Parylene N 10 µm	0.010

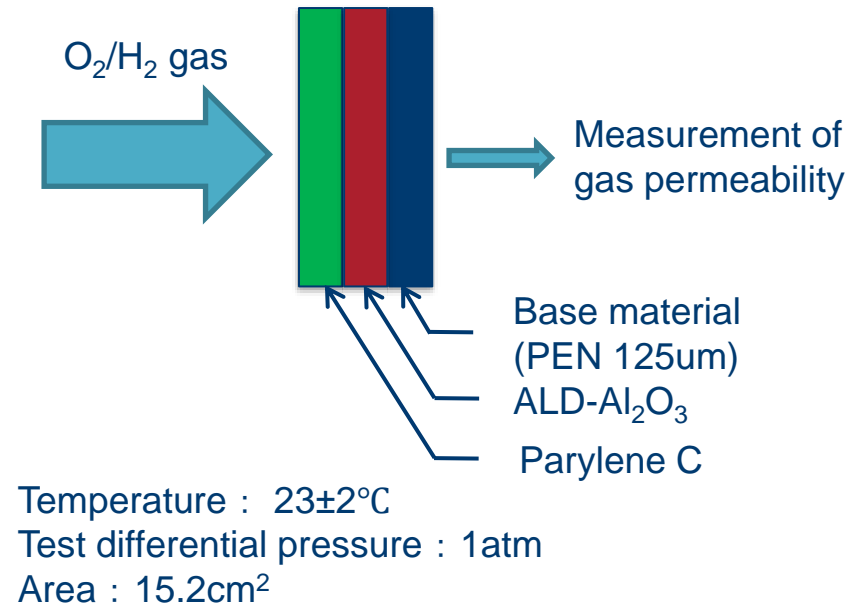


Measuring device: MOCON PERMATRAN-W 3/33. Measurement standard: JIS K 7129 : 2008

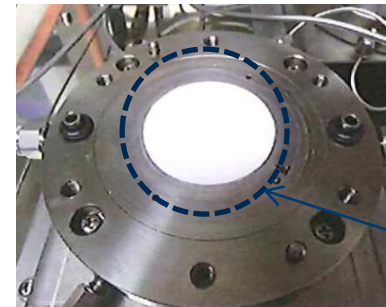
Device measurement lower limit value: 0.02g/(m<sup>2</sup> · 24h)

# Protection Performance Evaluation

## ► Study of Gas Barrier



### Sample shape



Area :  $15.2 cm^2$

Base material:  
Teijin DuPont films  
Teonex® PEN film  
polyethylene naphthalate film  
Q65FA 125um

Measuring device: Differential pressure gas measurement device GTR Tec Corporation GTR—30XAD2  
:Vapor transmission measurement device yanako G2700T · F  
Measurement standard: JIS K7126-1 : 2006 ( Differential pressure method )  
Device measurement lower limit value:  $0.05 (cm^3/m^2 \cdot 24h \cdot atm)$

# Gas Barrier: ALD/Parylene Coating

## ► Results of Gas Barrier

- The gas barrier property of Parylene-C was greatly improved adding ALD-Al<sub>2</sub>O<sub>3</sub> film (10 nm)

Deposition Condition	Gas Transmission			
	(cm <sup>3</sup> /m <sup>2</sup> · 24h · atm)		(mol/m <sup>2</sup> · s · Pa)	
	O <sub>2</sub>	H <sub>2</sub>	O <sub>2</sub>	H <sub>2</sub>
Parylene C film (10um)	3.84	198	1.96E-12	1.01E-14
ALD-Al <sub>2</sub> O <sub>3</sub> (10nm)	0.45	27.8	1.42E-16	2.76E-18
1 <sup>st</sup> layer ALD-Al <sub>2</sub> O <sub>3</sub> (10nm) + 2 <sup>nd</sup> layer Parylene C (10um)	< 0.05*	< 0.05*	< 5.00E-16*	< 5.00E-16*

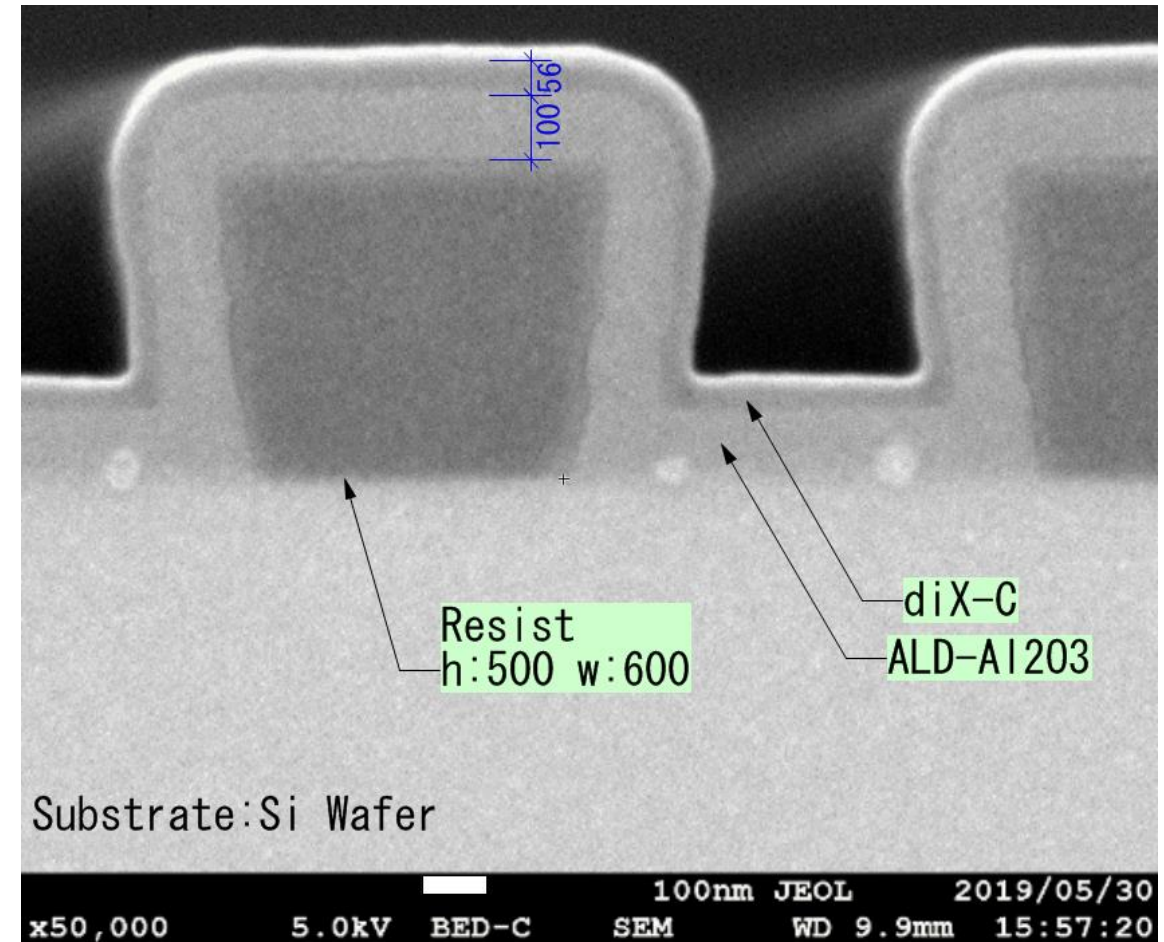
\*Regarding gas transmission, the oxygen/hydrogen gas data is lower than the detection limit of the measuring equipment.

\*\*Base material: Polyethylene naphthalate (PEN) 125um



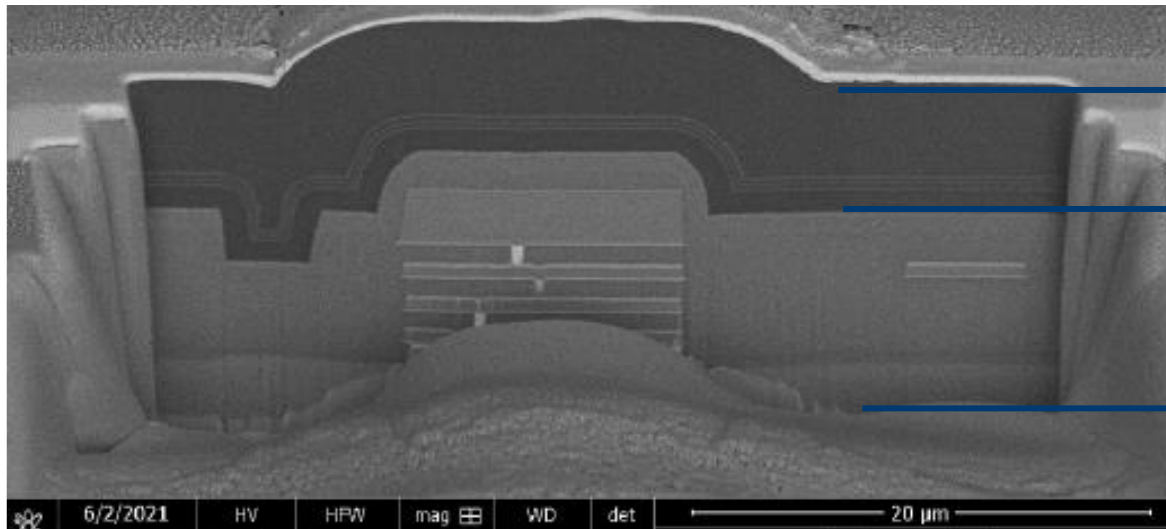
# Protection Performance Evaluation

- ▶ Study and result of step coverage
  - The resist film on the wafer was processed into a reverse tapered structure by etching to form ALD- $\text{Al}_2\text{O}_3$  100 nm + diX-C 56 nm, and the coverage was confirmed by SEM
  - Step coverage with good isotropy was confirmed from SEM photo



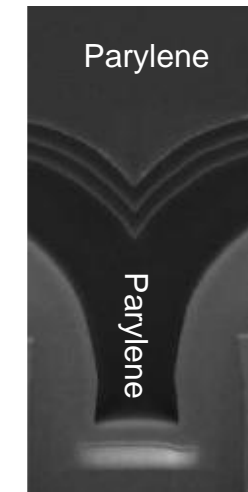
# Protection Performance Evaluation

- ▶ Study and result of step coverage
  - Step coverage with good isotropy was confirmed from FIB-SEM



Parylene – ALD multilayer

Substrate

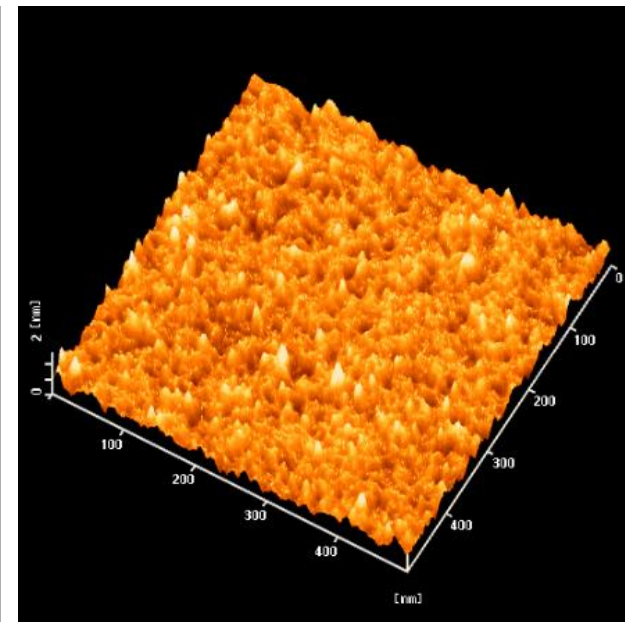
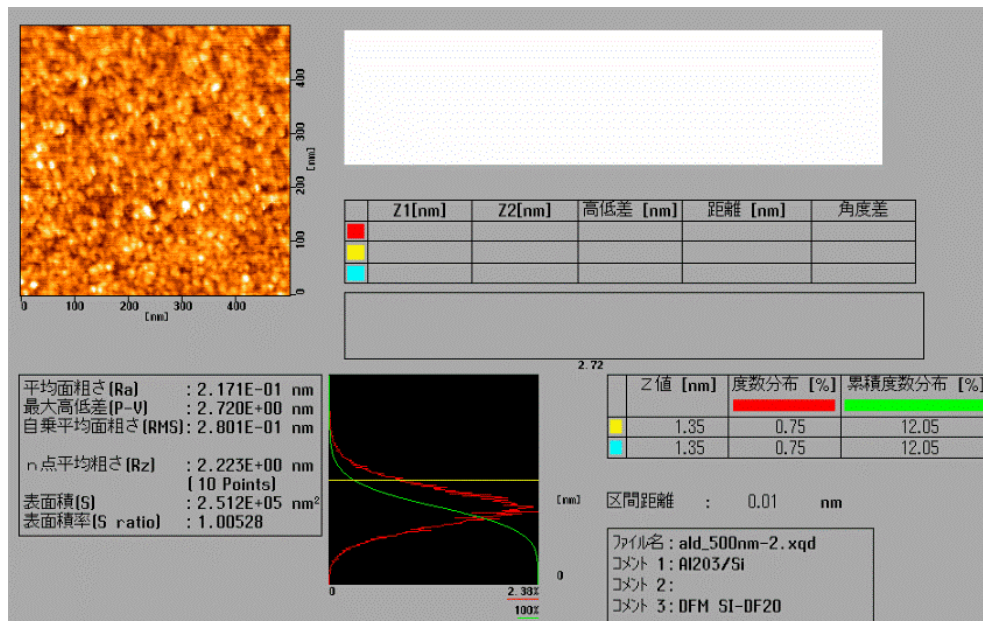


} 3 ALD layers

SEM-FIB micrograph of a chip coated with a Parylene-C – ALD ( $\text{TiO}_2\text{-Al}_2\text{O}_3$ ) multilayer

# Protection Performance Evaluation

- ▶ Study of surface flatness and pinhole-free
  - It was confirmed that the film was very flat, RMS: 0.28 nm
  - Per value of Ra: 0.22 nm, the film was a very dense
  - AFM images show neither cracks nor pin-holes



# Corrosion Resistance: Salt Solution Spray

## ► ALD/Parylene Coating

Salt Spray Tester



Substrate	1st layer	2nd layer
Based Material (Fe plate SPCC-SB)		Parylene C/0.5um
		Parylene C/1um
		Parylene C/3um
		Parylene C/5um
	ALD-Al <sub>2</sub> O <sub>3</sub> 10nm	Parylene C/0.5um
	ALD-Al <sub>2</sub> O <sub>3</sub> 10nm	Parylene C/1um
	ALD-Al <sub>2</sub> O <sub>3</sub> 10nm	Parylene C/3um
	ALD-Al <sub>2</sub> O <sub>3</sub> 10nm	Parylene C/5um

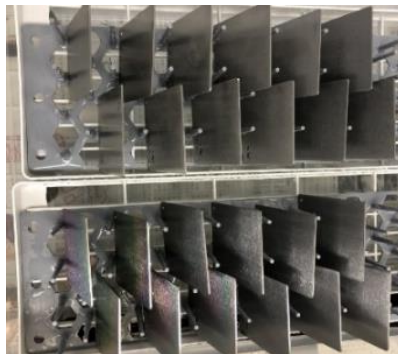
\*n=3

### Experimental conditions

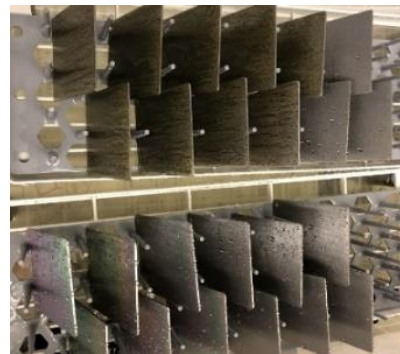
Based material: Fe plate SPCC-SB (JIS K2246B 1.2\* 60 \* 80)

Test solution : 50 ± 5 g/L NaCl solution (pH 6.5 ~ 7.2), 35±2°C

Flow rate is 5 L/min.



Ref



+15 min



+24 hours



+500 hours

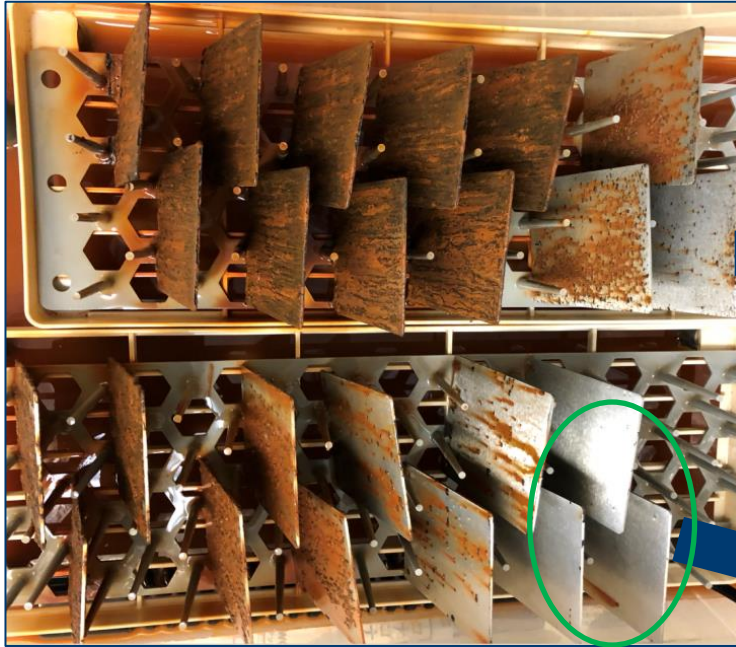
← Parylene C

← ALD+Parylene C

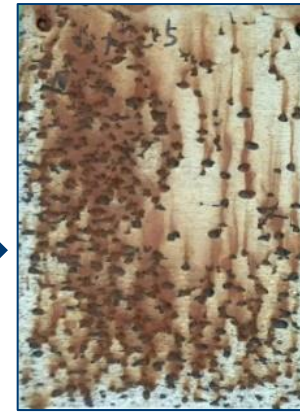


# Corrosion Resistance: Salt Solution Spray

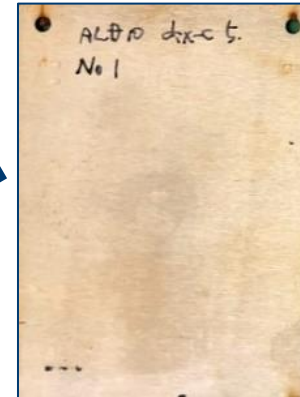
## ► ALD/Parylene Coating



Sample of Parylene C 5  $\mu\text{m}$   
corrosion occurred  
after 500 hours test



Sample of Parylene C 5  $\mu\text{m}$  +  
ALD  $\text{Al}_2\text{O}_3$  10nm has no  
corrosion after 500 hours test



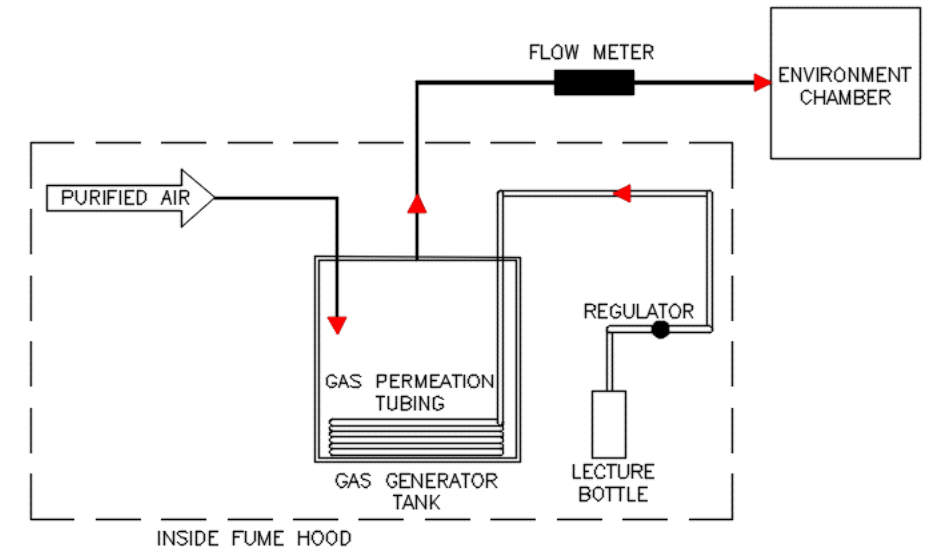
The above photo shows the status of sample after 500 hours. The film thickness is Parylene C 0.5, 1, 3, 5  $\mu\text{m}$ , from left to right. (Sample : n=3)

The upper right photo shows Parylene single layer on Fe plate; the lower photo shows ALD 10 nm in 1st layer and Parylene film in 2<sup>nd</sup> layer on Fe plate.

# Mixed Flow Gas Testing

## ► Testing Parameters

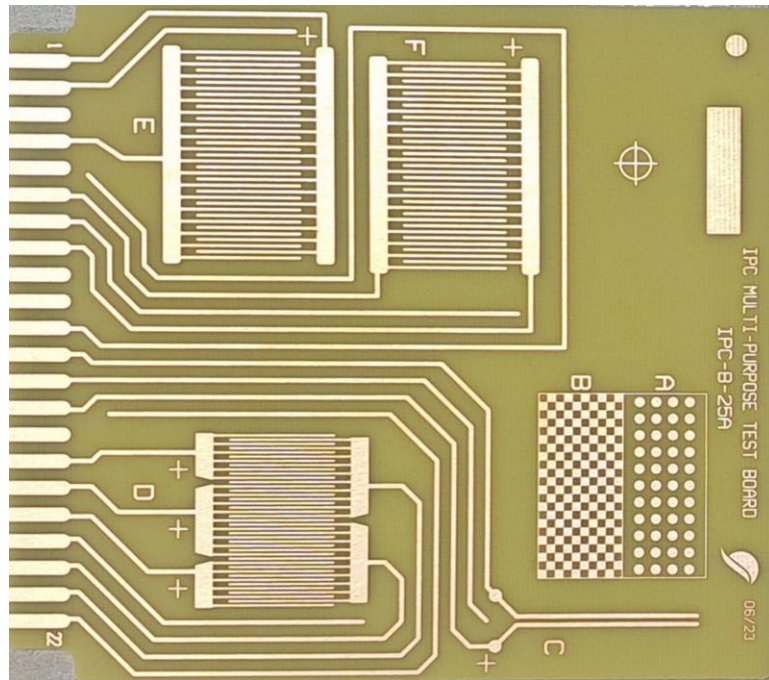
ASTM B845 Class IIIA MFG Test Parameters			
Cl <sub>2</sub> :	20±5 ppb	Relative Humidity:	70%±2%
NO <sub>2</sub> :	200±5 ppb	Temperature:	30°C±1°C
H <sub>2</sub> S:	100±5 ppb	Duration:	21
SO <sub>2</sub> :	200±5 ppb		



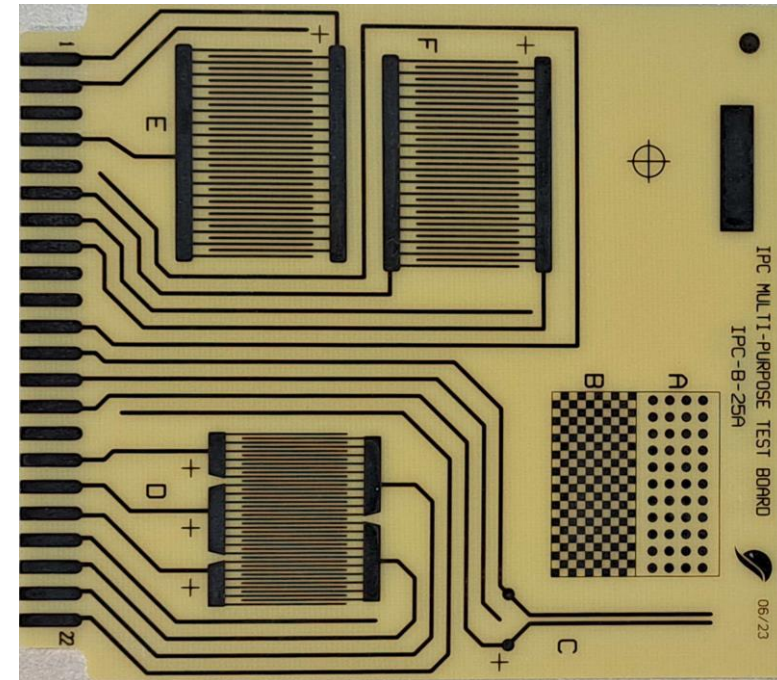
## ► Testing Lab: Battelle Advanced Materials

# MFG Testing – Control (Uncoated)

Day 0 (Before testing)



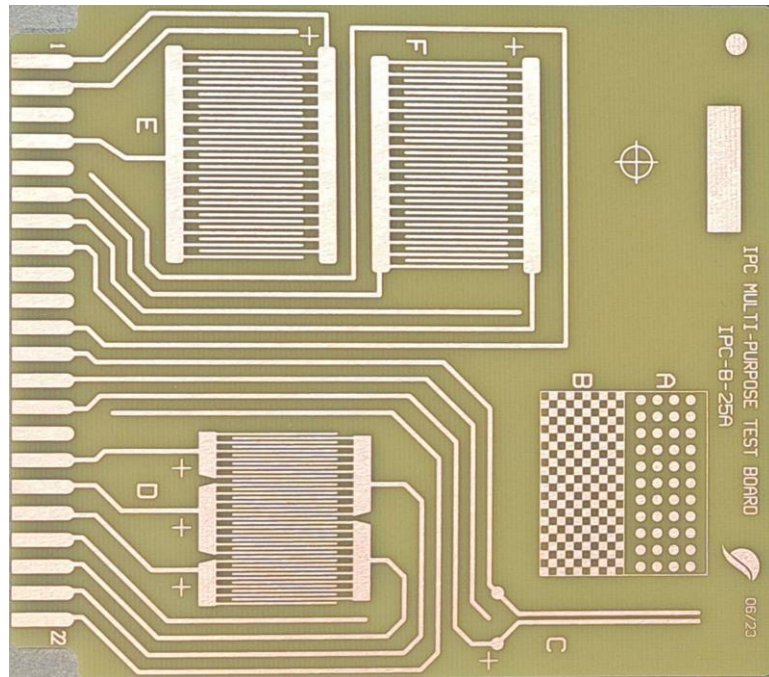
Day 21



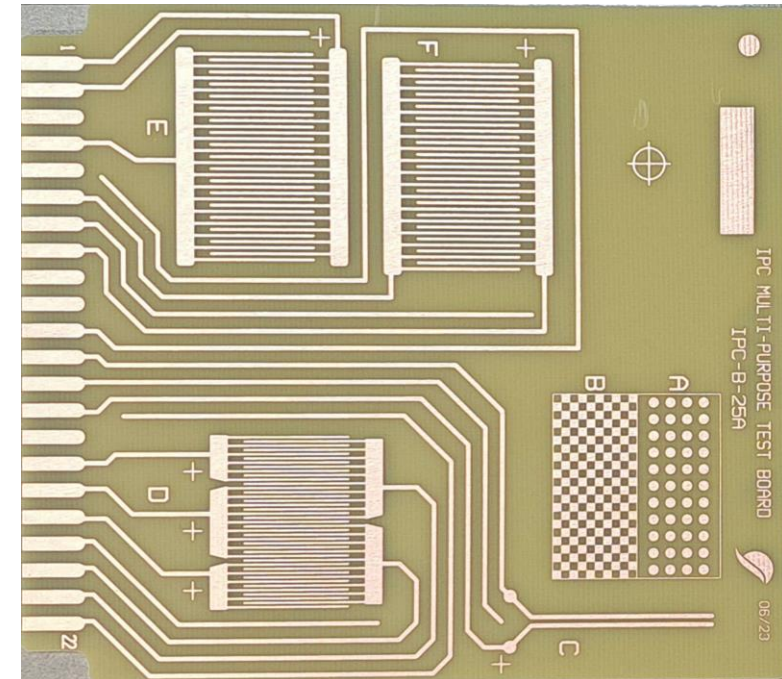


# MFG Testing: ALD + Parylene C 5um

Day 0 (Before testing)



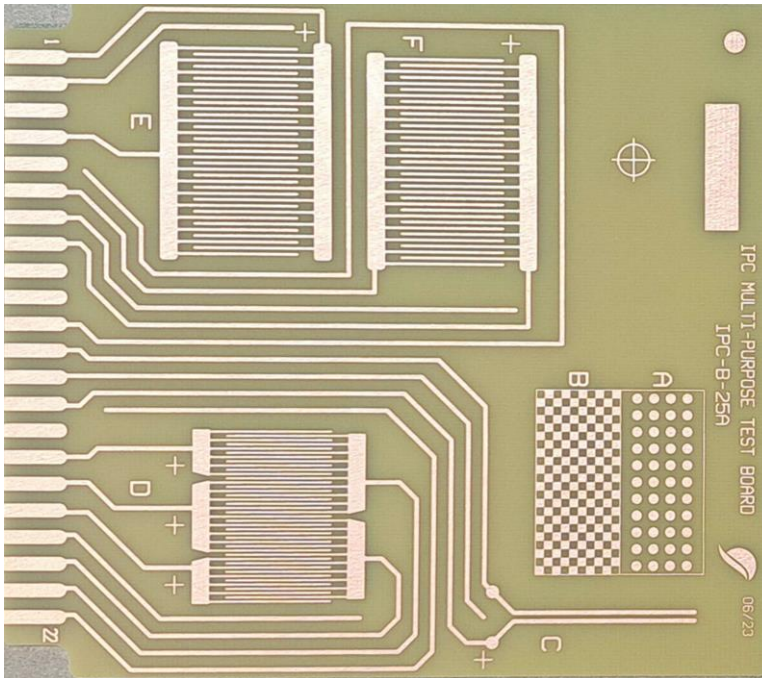
Day 21



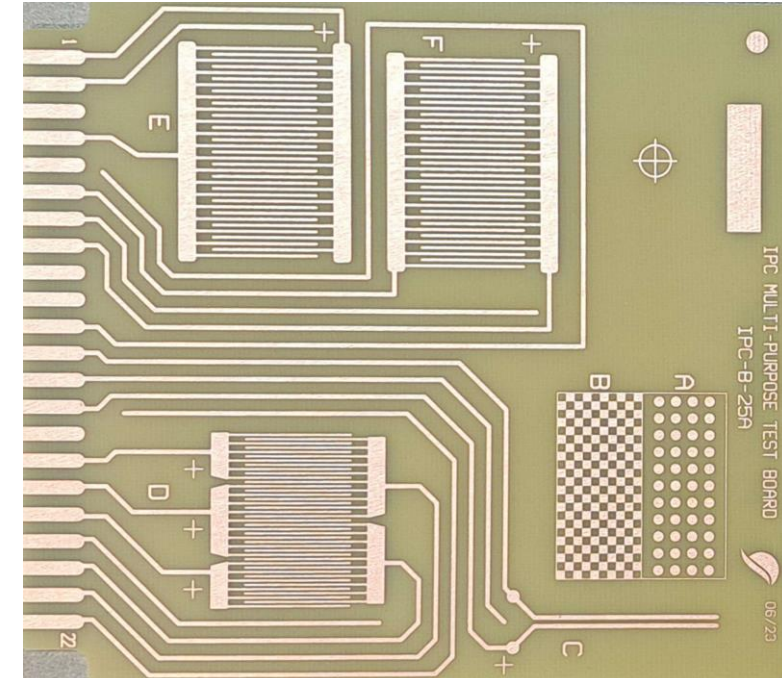


# MFG Testing –ALD + Parylene C 10um

Day 0 (Before testing)



Day 21



# Protection Performance Evaluation

- Real Life Application: PCBA coating with ALD-Parylene
  - Several PCBA were coated at one time (high volume capability)
  - 1st layer was ALD-Al<sub>2</sub>O<sub>3</sub>, 10 nm
  - 2nd layer : Parylene-C, 15  $\mu$ m

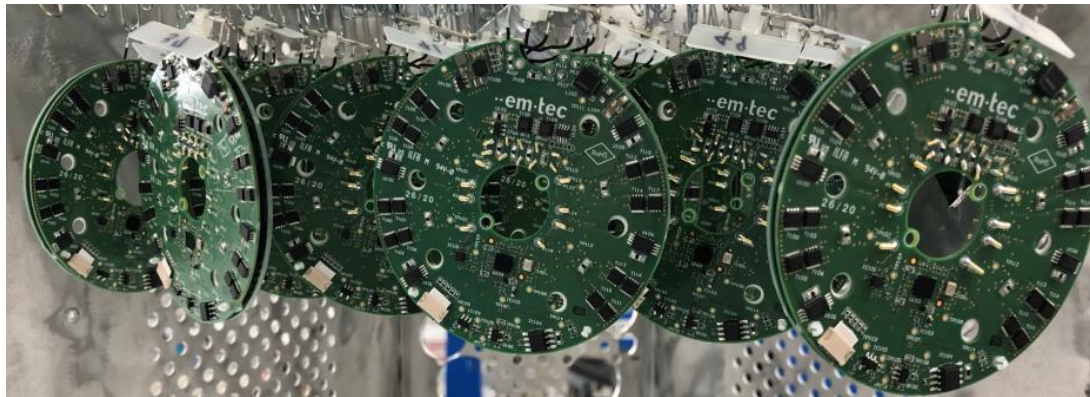


Photo Courtesy: Dr. Thomas Finocchiaro, ReinHeart TAH GmbH, Germany

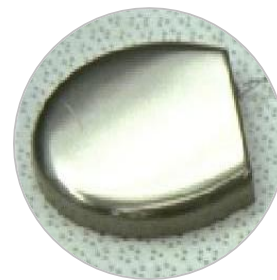


The diameter of the PCBA is 70 mm  
The thickness is 5mm

# Conclusion

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- ▶ Combining a thin layer of ALD with Parylene coating offers better protection of electronics, particularly against corrosion due to salt and other chemicals in harsh environments
- ▶ Excellent barrier properties at ultra-thin level
  - WVTR could be improved up to 100 times
  - In addition, parts coated with ALD-Parylene benefit from all key attributes of Parylene
  - Protects electronics and other devices against water splash and water immersion, IPX7 & IPX8 designations
  - Suitable for high frequency devices
  - Completely halogen-free when used with ParyFree, a new halogen-free variant of Parylene
  - Meets industry standards and regulatory compliances



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# Thank you for your attention

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- ▶ Specialty Coating Systems is the industry leader in conformal coating services and technologies for our global customers
- ▶ 21 coating facilities
  - Americas: US (8), Costa Rica
  - Europe: United Kingdom, Ireland, Czech Republic, Germany, Switzerland
  - Asia: China (2), Japan (2), Singapore, Thailand, Vietnam
- ▶ Manufacturing Standard Procedures (MSPs) to meet customer requirements
- ▶ Multiple locations to react to changes in requirements, volume ramp-up, natural disasters, etc.

## Contact Information:

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